

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2152	(@ad<"20021127") and 438/110, 113,458,460-465,976.ccls. and (cut or cutting or blade or saw or sawing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 12:10
L2	2165	(@ad<"20021127") and 438/110, 113,458,460-465,976.ccls. and (cut or cutting or blade or saw or sawing or cutter or cutters)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 12:11
L3	1498	L2 and (width or thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 12:11
L4	431	L2 and ((dual or second) with (cut or cutting or blade or saw or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 12:15
L5	1036	L2 and ((dual or second) with (substrates or substrate or wafer or wafers))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:24
L6	351	L5 and ((dual or second) with (cut or cutting or blade or saw or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:25
L7	1055	L2 and ((stack or dual or second) with (substrates or substrate or wafer or wafers))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:38
L8	352	L7 and ((dual or second) with (cut or cutting or blade or saw or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 12:16

L9	198	257/777,686.ccls. and ((dual or second) with (cut or cutting or blade or saw or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:20
L10	156	L9 and (width or thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:17
L11	151	L10 not L8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:18
L12	3498	"438"/\$.ccls. and (("t shape" or step or stepped) with (cut or cutting or blade or saw or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:37
L13	3520	"438"/\$.ccls. and (("t shape" or step or stepped) with (cut or cutting or blade or saw or teeth or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:24
L14	0	L:13 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:24
L15	2108	L13 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:24
L16	1360	L15 and ((dual or second) with (substrates or substrate or wafer or wafers))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:24

L17	351	L6 and ((dual or second) with (cut or cutting or blade or saw or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:25
L18	518	L16 and ((dual or second) with (cut or cutting or blade or saw or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:25
L19	440	"438"/\$.ccls. and (((wide or large or big) and (small or narraow or thin)) with (cut or cutting or blade or saw or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:38
L20	221	L19 and ((stack or dual or second) with (substrates or substrate or wafer or wafers))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:41
L21	219	L19 not L20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:41

L9	198	257/777,686.ccls. and ((dual or second) with (cut or cutting or blade or saw or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:20
L10	156	L9 and (width or thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:17
L11	151	L10 not L8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:18
L12	3498	"438"/\$.ccls. and (("t shape" or step or stepped) with (cut or cutting or blade or saw or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:22
L13	3520	"438"/\$.ccls. and (("t shape" or step or stepped) with (cut or cutting or blade or saw or teeth or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:24
L14	0	L:13 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:24
L15	2108	L13 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:24
L16	1360	L15 and ((dual or second) with (substrates or substrate or wafer or wafers))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:24

L17	351	L6 and ((dual or second) with (cut or cutting or blade or saw or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:25
L18	518	L16 and ((dual or second) with (cut or cutting or blade or saw or sawing or cutter or cutters))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/03 13:25